

IN THE CLAIMS:

Claims 10, 11 and 23 through 34 were previously cancelled. None of the claims have been amended herein. All of the pending claims are presented below for convenience of the Examiner. Please enter these claims as previously amended.

1. (Previously presented) A method for fabricating a chip-scale package, comprising:
positioning a preformed polymeric film including at least one aperture that extends substantially longitudinally therethrough over a semiconductor device with the at least one aperture in substantial alignment with a corresponding bond pad of the semiconductor device; and introducing conductive material in an at least partially liquid state into the at least one aperture.
2. (Previously presented) The method of claim 1, further comprising adhering the preformed polymeric film to the semiconductor device.
3. (Previously presented) The method of claim 1, further comprising defining at least another aperture through the preformed polymeric film.
4. (Previously presented) The method of claim 3, wherein defining is effected after positioning.
5. (Previously presented) The method of claim 3, wherein defining is effected before positioning.
6. (Previously presented) The method of claim 1, wherein introducing comprises bonding the conductive material to the corresponding bond pad.
7. (Previously presented) The method of claim 1, further comprising depositing conductive material onto the preformed polymeric film and within the at least one aperture.

8. (Previously presented) The method of claim 7, wherein depositing comprises chemical vapor depositing or physical vapor depositing the conductive material.

9. (Previously presented) The method of claim 1, wherein introducing comprises placing a preformed conductive structure within the at least one aperture.

10. (Cancelled)

11. (Cancelled)

12. (Previously presented) The method of claim 1, further comprising forming at least one contact at an end of the conductive material, opposite the semiconductor device.

13. (Previously presented) The method of claim 12, further comprising placing a conductive structure adjacent the at least one contact.

14. (Previously presented) The method of claim 13, wherein placing comprises applying solder to the at least one contact.

15. (Previously presented) The method of claim 1, further comprising positioning at least one conductive trace on the preformed polymeric film and in communication with the conductive material.

16. (Previously presented) The method of claim 15, further comprising forming at least one contact in communication with the conductive trace.

17. (Previously presented) The method of claim 16, further comprising placing a conductive structure adjacent the at least one contact.

18. (Previously presented) The method of claim 17, wherein placing comprises applying solder to the at least one contact.

19. (Previously presented) The method of claim 1, further comprising placing the preformed polymeric film on at least a portion of a peripheral edge of the semiconductor device.

20. (Previously presented) The method of claim 17, further comprising placing polymeric material at least laterally adjacent the conductive structure.

21. (Original) The method of claim 17, further comprising placing a conductive elastomer over at least one conductive structure.

22. (Previously presented) The method of claim 21, further comprising placing another conductive structure in contact with the conductive elastomer, opposite the at least one conductive structure.

23.-34. (Cancelled)